

PRODUCT DATA SHEET

HSMF Thermal Interface Material

Introduction

HSMF thermal interface material is a departure from our metallic TIM offering in that it is a non-silicon-based polymer. In order to supply this type of product to the industry, we required that it meet some specific criteria. This material resists pump out and bake out, performs better over time, and is easy to use. **HSMF** material meets these requirements. This rounds out Indium Corporation's offering to provide a full range of TIM materials.



Specifications

Pressure	10psi minimum to 500psi
Maximum operating temperature	200°C
Thickness	.010" or .006"

About this Product

HSMF is a compressible material for use in a wide range of applications requiring thermal transfer. Large area thermal interface requirements, such as IGBTs, benefit from the .010" thickness. This is also helpful for die-cast heat sinks with poor planarity. Assembly is efficient as this material has an inherent adhesive property, allowing for ease of placement. **HSMF** cleans up with IPA, making rework easy. Improved performance is ideal for long-life reliability as this material does not pump out or bake out in use over time. This material is electrically conductive.

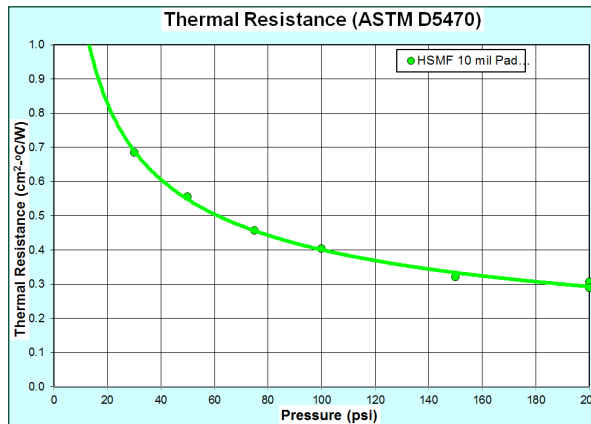
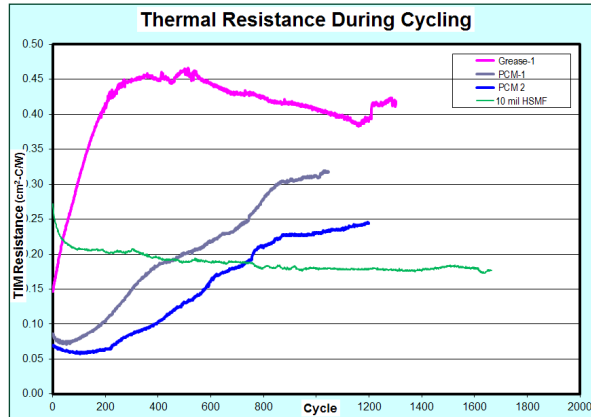
Storage and Packaging

HSMF can be provided in a variety of packaging configurations, depending on volume and size. If automation is required, tape & reel packaging is available.

Unused material should be stored in original packaging.

Safety Data Sheets

The SDS for this product can be found online at <http://www.indium.com/sds>



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